J (R−GDIP−T**)  
14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE

<table>
<thead>
<tr>
<th>DIM</th>
<th>14</th>
<th>16</th>
<th>18</th>
<th>20</th>
</tr>
</thead>
<tbody>
<tr>
<td>A</td>
<td>0.300 (7,62) BSC</td>
<td>0.300 (7,62) BSC</td>
<td>0.300 (7,62) BSC</td>
<td>0.300 (7,62) BSC</td>
</tr>
<tr>
<td>B</td>
<td>0.785 (19,94)</td>
<td>0.840 (21,34)</td>
<td>0.960 (24,38)</td>
<td>1.060 (26,92)</td>
</tr>
<tr>
<td>C</td>
<td>0.300 (7,62)</td>
<td>0.300 (7,62)</td>
<td>0.310 (7,87)</td>
<td>0.300 (7,62)</td>
</tr>
</tbody>
</table>

| C MIN | 0.245 (6,22) | 0.245 (6,22) | 0.220 (5,59) | 0.245 (6,22) |

NOTES:  
A. All linear dimensions are in inches (millimeters).  
B. This drawing is subject to change without notice.  
C. This package is hermetically sealed with a ceramic lid using glass frit.  
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.  
E. Falls within MIL STD 1835 GDIP1−T14, GDIP1−T16, GDIP1−T18 and GDIP1−T20.
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